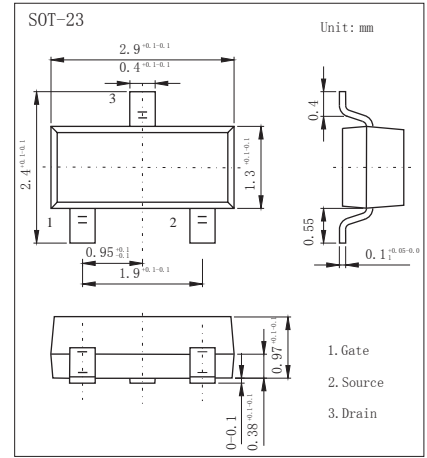
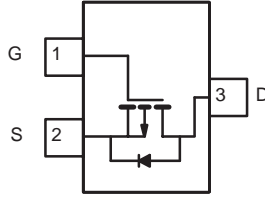


# P-Channel Enhancement MOSFET

## RC2309A

### ■ Features

- $V_{DS}(V)=-60V$
- $I_D=-2A$  ( $V_{GS}=-10V$ )
- $R_{DS(ON)} < 200m\Omega$  ( $V_{GS}=-10V$ )
- $R_{DS(ON)} < 240m\Omega$  ( $V_{GS}=-4.5V$ )



### ■ Marking

Marking	MS09
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### ■ Maximum ratings ( $T_a=25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	-60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current	$I_D$	-2	A
Pulsed Drain Current	$I_{DM}$	-8	
Power Dissipation	$P_D$ <sup>④</sup>	1.56	W
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$ <sup>④</sup>	80	$^{\circ}C/W$
Operation Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 ~ +150	$^{\circ}C$

# P-Channel Enhancement MOSFET

## RC2309A

### ■ MOSFET ELECTRICAL CHARACTERISTICS

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-60			V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = -60V, V_{GS} = 0V, T_J = 25^\circ C$			-1	$\mu A$
		$V_{DS} = -60V, V_{GS} = 0V, T_J = 125^\circ C$			-1	mA
Gate-source leakage current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$			$\pm 100$	nA
<b>On characteristics</b>						
Drain-source on-resistance <sup>②</sup>	$R_{DS(on)}$	$V_{GS} = -10V, I_D = -2A$		160	200	m $\Omega$
		$V_{GS} = -4.5V, I_D = -1.5A$		195	240	m $\Omega$
Forward transconductance	$g_{FS}$	$V_{DS} = -10V, I_D = -2A$		3.5		S
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-1.0	-1.5	-2.5	V
<b>Dynamic Characteristics<sup>③</sup></b>						
Input capacitance	$C_{iss}$	$V_{DS} = -30V, V_{GS} = 0V, f = 1MHz$		425	615	pF
Output capacitance	$C_{oss}$			35	50	pF
Reverse transfer capacitance	$C_{rss}$			20	30	pF
Gate resistance	$R_g$	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$		17		$\Omega$
<b>Switching Characteristics<sup>③</sup></b>						
Turn-on delay time	$t_{d(on)}$	$V_{GS} = -10V, V_{DD} = -30V, I_D = -1A, R_G = 6\Omega$		5.2	10	ns
Turn-on rise time	$t_r$			19	36	ns
Turn-off delay time	$t_{d(off)}$			35	67	ns
Turn-off fall time	$t_f$			10.6	20	ns
Total Gate Charge	$Q_g$	$V_{DS} = -30V, I_D = -2A, V_{GS} = -10V$		8.2	12	nC
Gate-Source Charge	$Q_{gs}$			1.8	3.6	nC
Gate-Drain Charge	$Q_{gd}$			1.5	3	nC
<b>Drain-source diode characteristics and maximum ratings</b>						
Diode forward voltage <sup>②</sup>	$V_{SD}$	$I_S = -1A, V_{GS} = 0V$		-0.83	-1	V
Continuous drain-source diode forward current	$I_S$				-2	A
Pulsed drain-source diode forward current <sup>①</sup>	$I_{SM}$				-8	A

Notes:

1.Repetitive Rating : Pulse width limited by maximum junction temperature.

2.Pulse Test : Pulse Width $\leq$ 300 $\mu$ s, Duty Cycle  $\leq$  2%.

3.Guaranteed by design, not subject to production testing.

4.The value of R $\theta$ JA is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with Ta=25  $^\circ$ C.

# P-Channel Enhancement MOSFET RC2309A

## Typical Characteristics

